

In re Patent Application of: KOHEI TATSUNAMI ET AL.

Serial No.09/254,118

Examiner: MICHAEL DIETRICH

Filed: May 19, 1999

Group Art Unit: 2814

For: METHOD OF PARTIALLY PLATING SUBSTRATE FOR ELECTRONIC DEVICES



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Shun  
12-11-00*

TRANSLATOR'S DECLARATION

Honorable Commissioner of Patents & Trademarks  
Washington, D.C. 20231

Sir:

I, Kenichi Tsunakawa, residing at c/o A. AOKI, ISHIDA & ASSOCIATES, Toranomom 37 Mori Bldg., 3-5-1, Toranomom Minato-ku, Tokyo 105-8423, Japan declare the following:

(1) That I know well both the Japanese and English languages;

(2) That I translated Japanese Patent Application No. 8-244268, filed August 27, 1996, from the Japanese language to the English language;

(3) That the attached English translation is a true and correct translation of the aforesaid Japanese Patent Application No. 8-244268 to the best of my knowledge and belief; and

(4) That all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements are made with the knowledge that willful false statements and the like are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001, and that such false statements may jeopardize the validity of the application or any patent issuing thereon.

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August 18, 2000

Date

Kenichi Tsunakawa  
Translator Kenichi Tsunakawa